SPECIFICATIONS FOR WARM WHITE LED **NICHIA CORPORATION**

NSBLL110-H3

- Built-in ESD Protection Device
- RoHS Compliant



SPECIFICATIONS

(1) Absolute Maximum Ratings

| Item | Symbol | Absolute Maximum Rating | Unit |
|---------------------------------------|------------------|-------------------------|------|
| Forward Current | ${ m I}_{\sf F}$ | 600 | mA |
| Pulse Forward Current I _{FP} | | 900 | mA |
| Allowable Reverse Current | I_{R} | 85 | mA |
| Power Dissipation | P_{D} | 21.6 | W |
| Operating Temperature | T_{opr} | -40~100 | °C |
| Storage Temperature | T_{stg} | -40~100 | °C |
| Junction Temperature | Tı | 130 | °C |

^{*} Absolute Maximum Ratings at $T_C=25$ °C.

(2) Initial Electrical/Optical Characteristics

| Item | Item | | Condition | Тур | Max | Unit |
|-------------------------|-----------------|-----------------|-----------------------|--------|-----|------|
| Forward Voltage | | V_{F} | I _F =320mA | 33.3 | - | V |
| B0000 | Luminous Flux | Ф | I _F =320mA | 990 | - | lm |
| R8000 | Color Rendering | R_a | I _F =320mA | 85 | - | ı |
| | Х | - | I _F =320mA | 0.4338 | - | ı |
| Chromaticity Coordinate | у | - | I _F =320mA | 0.4030 | - | - |
| Thermal Resistance | | $R_{\theta JC}$ | - | 1.8 | 2.1 | °C/W |

^{*} Characteristics at $T_C=25^{\circ}C$.

^{*} I_{FP} conditions with pulse width $\leq 10 \text{ms}$ and duty cycle $\leq 10 \%$.

 $[\]boldsymbol{*}$ The operating Temperature (T $_{\text{opr}}$) range is the range of case temperatures.

^{*} Luminous Flux value as per CIE 127:2007 standard.

^{*} Chromaticity Coordinates as per CIE 1931 Chromaticity Chart.

^{*} $R_{\theta JC}$ is Thermal Resistance from junction to T_{C} measuring point.

RANKS

| Item | Rank | | Min | Max | Unit |
|-----------------|-----------------------|----------------|------|------|------|
| Forward Voltage | - | | 30 | 36 | V |
| | J1000 J850 J700 | | 1000 | 1150 | |
| Luminous Flux | | | 850 | 1000 | lm |
| | | | 700 | 850 | |
| | | Ra | 80 | - | - |
| Color Rendering | R8000 | R ₉ | 0 | - | - |

Color Ranks

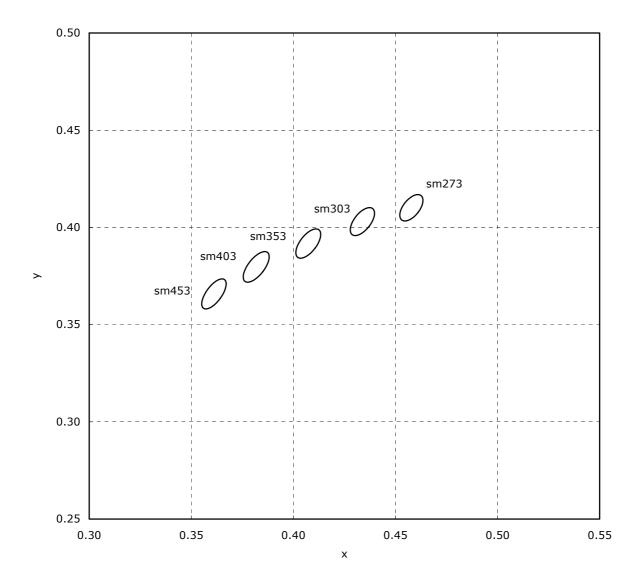
| | | Rank sm273 | Rank sm303 | Rank sm353 | Rank sm403 | Rank sm453 |
|--------------|---|------------|------------|------------|------------|------------|
| | х | 0.4578 | 0.4338 | 0.4073 | 0.3818 | 0.3611 |
| Center Point | У | 0.4101 | 0.4030 | 0.3917 | 0.3797 | 0.3658 |

- * Ranking at $T_C=25$ °C.
- * Tolerance of measurements of the Forward Voltage is ± 0.41 V.
- * Tolerance of measurements of the Luminous Flux is $\pm 7\%$.
- * Tolerance of measurements of the Color Rendering R_{a} is ± 2 .
- * Tolerance of measurements of the Color Rendering R_{9} is $\pm 6.5.\,$
- * The R_9 value for the above rank shall be greater than 0.
- * Tolerance of measurements of the Chromaticity Coordinate is ± 0.005 .
- * The color rank has a chromaticity range within a 3-step MacAdam ellipse.
- * A shipment shall consist of LEDs in a combination of the above ranks.

 The percentage of each rank in the shipment shall be determined by Nichia.

Luminous Flux Ranks by Color Rank, Color Rendering Rank

| Ranking by Color Coordinates, Color Rend | Ranking by Luminous Flux lering | J700 | J850 | J1000 |
|--|---------------------------------|------|------|-------|
| sm273,sm303 | R8000 | | | |
| sm353, sm403,sm453 | R8000 | | | |

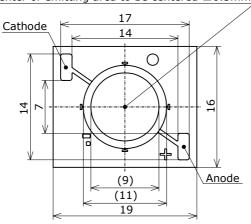


OUTLINE DIMENSIONS

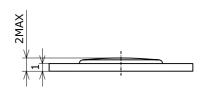
* 本製品はRoHS指令に適合しております。 This product complies with RoHS Directive. NSBxL110-H3 管理番号 No. STS-DA7-0078A

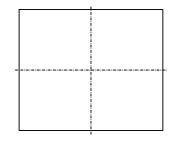
(単位 Unit: mm, 公差 Tolerance: ±0.3)

発光部中心の位置精度 ± 0.3 mm The center of emitting area to be centered ± 0.3 mm.

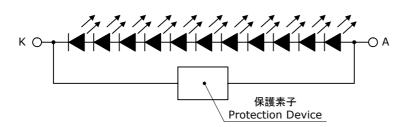








| 項目 Item | 内容 Description | |
|--|---|--|
| パッケージ材質 Package Materials | セラミックス Ceramics | |
| 封止樹脂材質 Encapsulating Resin Materials | シリコーン樹脂 (蛍光体入り) Silicone Resin (with phosphor) | |
| 電極材質 Electrodes Materials | 金メッキ Au-plated | |
| 質量 Weight | 1.2g (TYP) | |



SOLDERING

• Recommended Hand Soldering Condition

| Temperature | 380°C Max |
|----------------|-----------|
| Soldering Time | 5sec Max |

- * Hand soldering must not be performed more than once.
- * Since the silicone used in the encapsulating resin frame is soft, do not press on the encapsulating resin frame or resin area.

 Pressure can cause nicks, chip-outs, encapsulant delamination and deformation, and wire breaks, decreasing reliability.
- * Repairing should not be done after the LEDs have been soldered.

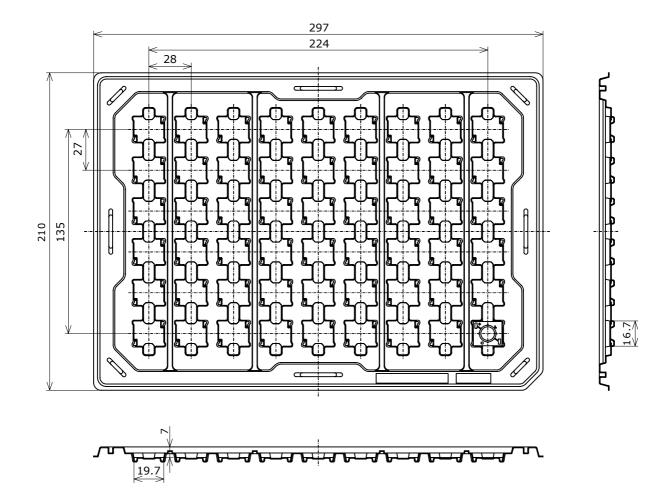
 It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- $\ensuremath{^{*}}$ When soldering, do not apply stress to the LED while the LED is hot.

TRAY DIMENSIONS

* 数量は1トレイにつき 54個入りです。 Quantity per tray=54pcs

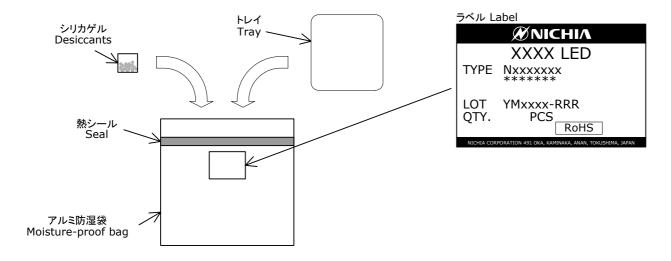
* 寸法は参考です。 All dimensions shown are for reference only and are not guaranteed. NxxxL110x 管理番号 No. STS-DA7-0055A

(単位 Unit: mm)

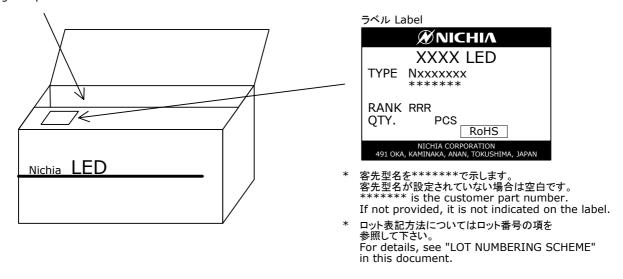


PACKAGING - TRAY PACK

シリカゲルとともにトレイをアルミ防湿袋に入れ、熱シールにより封をします。 Trays are shipped with desiccants in heat-sealed moisture-proof bags. Nxxxxxxx 管理番号 No. STS-DA7-0007B



アルミ防湿袋を並べて入れ、ダンボールで仕切ります。 Moisture-proof bags are packed in cardboard boxes with corrugated partitions.



- 本製品はトレイに入れたのち、輸送の衝撃から保護するためダンボールで梱包します。
 Products shipped on trays are packed in a moisture-proof bag.
 They are shipped in cardboard boxes to protect them from external forces during transportation.
- * 取り扱いに際して、落下させたり、強い衝撃を与えたりしますと、製品を損傷させる原因になりますので注意して下さい。 Do not drop or shock the box. It may damage the products.
- * ダンボールには防水加工がされておりませんので、梱包箱が水に濡れないよう注意して下さい。 Do not expose to water, the box is not water-resistant.
- * 輸送、運搬に際して弊社よりの梱包状態あるいは同等の梱包を行って下さい。
 Using an original packaging material or equivalent in transit is recommended.

LOT NUMBERING SCHEME

Lot Number is presented by using the following alphanumeric code.

YMxxxx - RRR

Y - <u>Year</u>

| Year | Y |
|------|---|
| 2009 | 9 |
| 2010 | А |
| 2011 | В |
| 2012 | С |
| 2013 | D |
| 2014 | Е |

M - Month

| Month | М | Month | М |
|-------|---|-------|---|
| 1 | 1 | 7 | 7 |
| 2 | 2 | 8 | 8 |
| 3 | 3 | 9 | 9 |
| 4 | 4 | 10 | Α |
| 5 | 5 | 11 | В |
| 6 | 6 | 12 | С |

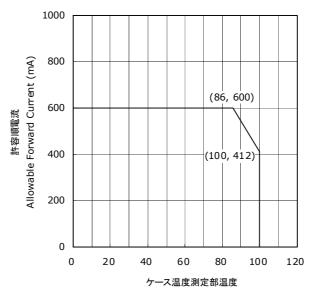
xxxx-Nichia's Product Number

RRR-Ranking by Color Coordinates, Ranking by Luminous Flux, Ranking by Color Rendering

NSBxL110-H3 管理番号 No. STS-DA7-0074A

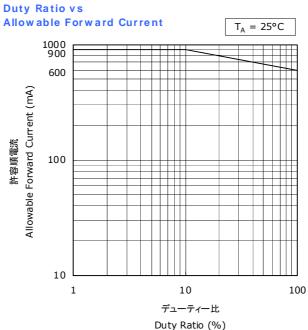
ケース温度測定部温度 - 許容順電流特性

Temperature at Measure Point on a Case vs Allowable Forward Current



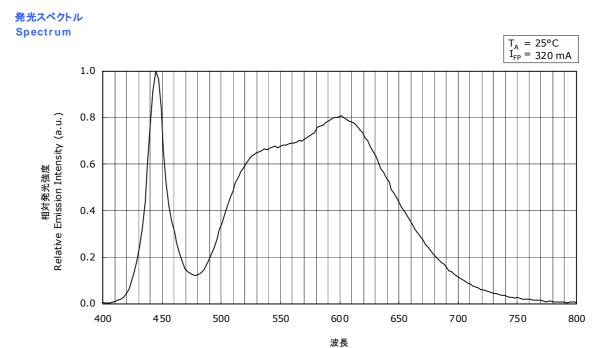
Temperature at Measure Point on a Case (°C)

デューティー比 - 許容順電流特性

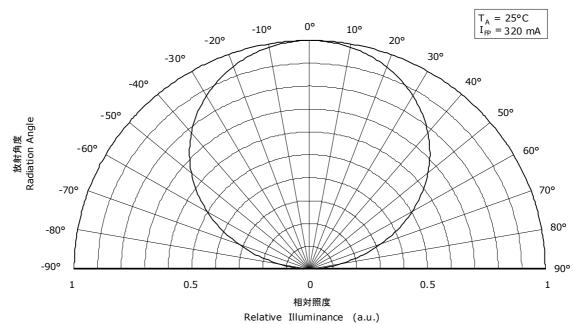


OPTICAL CHARACTERISTICS

* 本特性は参考です。 All characteristics shown are for reference only and are not guaranteed. NSBLL110-H3 管理番号 No. STS-DA7-0075



指向特性 Directivity



Wavelength (nm)

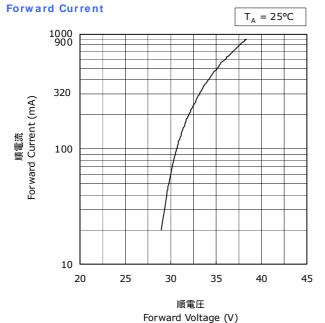
NSBLL110-H3

STS-DA7-0076

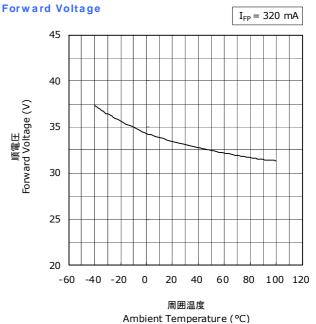
FORWARD CURRENT CHARACTERISTICS / TEMPERATURE CHARACTERISTICS

* 本特性は参考です。
All characteristics shown are for reference only and are not guaranteed. 管理番号 No.

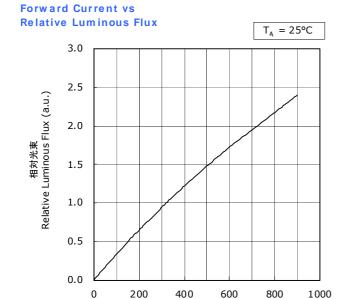
順電圧 一順電流特性 Forward Voltage vs



周囲温度 - 順電圧特性 Ambient Temperature vs



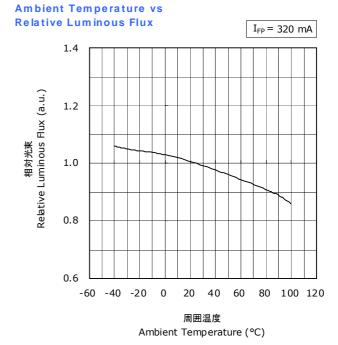
順電流 - 相対光東特性



順電流

Forward Current (mA)

周囲温度 - 相対光束特性



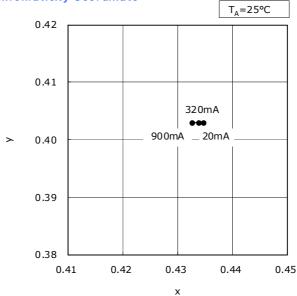
FORWARD CURRENT CHARACTERISTICS / TEMPERATURE CHARACTERISTICS

* 本特性は参考です。 All characteristics shown are for reference only and are not guaranteed. 管理都

NSBLL110-H3 管理番号 No. STS-DA7-0077A

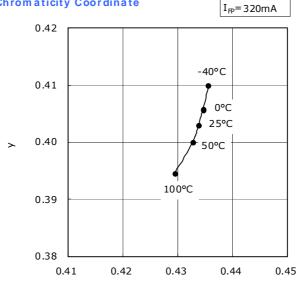


Forward Current vs Chromaticity Coordinate



周囲温度-色度特性

Ambient Temperature vs Chromaticity Coordinate



RELIABILITY

(1) Tests and Results

| Test | Reference Standard | Test Conditions | Test Duration | Failure Criteria # | Units Failed/Tested |
|---------------------------------|--------------------------|---|------------------|--------------------------|------------------------|
| Temperature Cycle | JEITA ED-4701 100 105 | -40°C(30min)~25°C(5min)~ 100°C(30min)~25°C(5min) | 100cycles | #1 | 0/10 |
| High Temperature Storage | JEITA ED-4701 200 201 | T _A =100°C | 1000hours | #1 | 0/10 |
| Temperature Humidity Storage | JEITA ED-4701 100 103 | T _A =60°C, RH=90% | 1000hours | #1 | 0/10 |
| Low Temperature Storage | JEITA ED-4701 200 202 | T _A =-40°C | 1000hours | #1 | 0/10 |
| High Temperature Operating Life | | T _C =85°C, I _F =600mA | 1000hours | #1 | 0/10 |
| Electrostatic Discharges | JEITA ED-4701 300 304 | HBM, 2kV, $1.5k\Omega$, $100pF$, $3pulses$, alternately positive or negative | | #1 | 0/10 |

NOTES:

Measurements are performed after allowing the LEDs to return to room temperature.

(2) Failure Criteria

| Criteria # | Items | Conditions | Failure Criteria |
|------------|----------------------------------|-----------------------|---|
| | Forward Voltage(V _F) | I _F =320mA | >Initial value×1.1 |
| #1 | Luminous Flux(Φ _V) | I _F =320mA | <initial td="" value×0.7<=""></initial> |

CAUTIONS

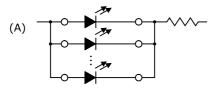
(1) Storage

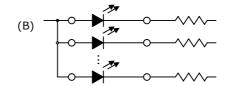
| Conditions | | Temperature | Humidity | Time |
|------------|-----------------------------|-------------|----------|----------------------------------|
| | Before Opening Aluminum Bag | ≤30°C | ≤90%RH | Within 1 Year from Delivery Date |
| Storage | After Opening Aluminum Bag | ≤30°C | ≤70%RH | ≤168hours |

- After opening the moisture-proof aluminum bag, the products should go through the soldering process within the range of the conditions stated above. Unused remaining LEDs should be stored with silica gel desiccants in a hermetically sealed container, preferably the original moisture-proof bags for storage.
- Customer is advised to keep the LEDs in an airtight container when not in use. Exposure to a corrosive environment may cause the plated metal parts of the product to tarnish, which could adversely affect optical characteristics. It is also recommended to return the LEDs to the original moisture proof bags and reseal.
- After assembly and during use, silver plating can be affected by the corrosive gases emitted by components and materials
 in close proximity of the LEDs within an end product, and the gases entering into the product from the external atmosphere.
 The above should be taken into consideration when designing.
 Resin materials, in particular, may contain substances which can affect silver plating, such as halogen.
- Do not use sulfur-containing materials in commercial products. Some materials, such as seals and adhesives, may contain sulfur. The extremely corroded or contaminated plating of LEDs might cause an open circuit. Silicone rubber is recommended as a material for seals. Bear in mind, the use of silicones may lead to silicone contamination of electrical contacts inside the products, caused by low molecular weight volatile siloxane.
- To prevent water condensation, please avoid large temperature and humidity fluctuations for the storage conditions.

(2) Directions for Use

When designing a circuit, the current through each LED must not exceed the Absolute Maximum Rating.
 Operating at a constant current per LED is recommended. In case of operating at a constant voltage, Circuit B is recommended.
 If the LEDs are operated with constant voltage using Circuit A, the current through the LEDs may vary due to the variation in Forward Voltage characteristics of the LEDs.





- LEDs should be operated in forward bias. Driving circuits must not subject LEDs to either forward or reverse voltage while off.

 Continuous reverse voltage can cause migration and LED damage.
- Pulse width modulation (PWM) is recommended for dimming LEDs as color point changes with drive current.
- For stabilizing the LED characteristics, it is recommended to operate at greater than 10% nominal current.
- For outdoor use, necessary measures should be taken to prevent water, moisture and salt air damage.

(3) Handling Precautions

- Do not handle LEDs with bare hands, it may contaminate the LED surface and affect optical characteristics.

 In the worst case, catastrophic failure from excess pressure through wire-bond breaks and package damage may result.
- When handling the product with tweezers, be careful not to apply excessive force to the resin.

 Otherwise, The resin can be cut, chipped, delaminate or deformed, causing wire-bond breaks and catastrophic failures.
- Dropping the product may cause damage.
- Do not stack assembled the products. Failure to comply can cause the resin portion of the product to be cut, chipped, delaminated and/or deformed. It may cause wire to break, leading to catastrophic failures.

(4) Design Consideration

- Excessive forces on this product can cause the ceramic package to crack. It is recommended to use a holder when fixing this product to a chassis.
- It is recommended to use a thermal film or thermal grease between the product and a chassis for increased heat dissipation.

(5) Electrostatic Discharge (ESD)

• The products are sensitive to static electricity or surge voltage. ESD can damage a die and its reliability.

When handling the products, the following measures against electrostatic discharge are strongly recommended:

Eliminating the charge

Grounded wriststrap, ESD footwear, clothes, and floors

Grounded workstation equipment and tools

ESD table/shelf mat made of conductive materials

• Proper grounding is required for all devices, equipment, and machinery used in product assembly. Surge protection should be considered when designing of commercial products.

• If tools or equipment contain insulating materials such as glass or plastic,

the following measures against electrostatic discharge are strongly recommended:

Dissipating static charge with conductive materials

Preventing charge generation with moisture

Neutralizing the charge with ionizers

(6) Thermal Management

- Proper thermal management is an important when designing products with LEDs. LED die temperature is affected by LED module thermal resistance and LED spacing. Please design products in a way that the LED die temperature does not exceed the maximum Junction Temperature (T_J).
- The dice temperature of the products should be calculated, using the case temperature (T_c) of the product incorporated into the end-product, by the following equation.

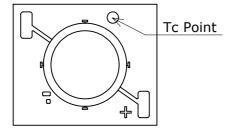
$$T_J = T_C + R_{\theta JC} \cdot W$$

*T_J=LED junction temperature: °C

 T_C =Case temperature (cathode side): °C

 $R_{\theta JC}$ =Thermal resistance from junction to T_C measuring point: ${}^{\circ}C/W$

W=Input power($I_F \times V_F$): W



(7) Cleaning

- If required, isopropyl alcohol (IPA) should be used. Other solvents may cause premature failure to the LEDs due to the damage to the resin portion. The effects of such solvents should be verified prior to use.

 In addition, the use of CFCs such as Freon is heavily regulated.
- Ultrasonic cleaning is not recommended since it may have adverse effects on the LEDs depending on the ultrasonic power and how LED is assembled.

If ultrasonic cleaning must be used, the customer is advised to make sure the LEDs will not be damaged prior to cleaning.

(8) Eye Safety

• In 2006, the International Electrical Commission (IEC) published IEC 62471:2006 Photobiological safety of lamps and lamp systems, which added LEDs in its scope.

On the other hand, the IEC 60825-1:2007 laser safety standard removed LEDs from its scope.

However, please be advised that some countries and regions have adopted standards

based on the IEC laser safety standard IEC 60825-1:20112001, which still includes LEDs in its scope.

Most of Nichia's LEDs can be classified as belonging into either the Exempt Group or Risk Group 1.

High-power LEDs, that emit light containing blue wavelengths, may be classified as Risk Group 2.

Please proceed with caution when viewing directly any LEDs driven at high current, or viewing LEDs with optical instruments which may greatly increase the damages to your eyes.

• Viewing a flashing light may cause eye discomfort. When incorporating the LED into your product, please be careful to avoid adverse effects on the human body caused by light stimulation.

(9) Others

- The LEDs described in this brochure are intended to be used for ordinary electronic equipment (such as office equipment, communications equipment, measurement instruments and household appliances).
 Consult Nichia's sales staff in advance for information on the applications in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as for airplanes, aerospace, submersible repeaters, nuclear reactor control system, automobiles, traffic control equipment, life support systems and safety devices).
- The customer shall not reverse engineer by disassembling or analysis of the LEDs without having prior written consent from Nichia. When defective LEDs are found, the customer shall inform Nichia directly before disassembling or analysis.
- Both the customers and Nichia will agree on official specifications of supplied products before a customer's volume production.
- Specifications and appearance subject to change for improvement without notice.